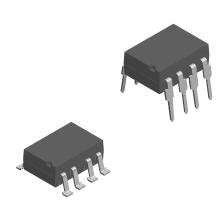
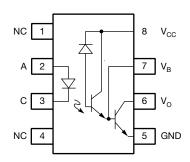


High Speed Optocoupler, 100 kBd, Low Input Current, Photodiode Darlington Output





LINKS TO ADDITIONAL RESOURCES











DESCRIPTION

High common mode transient immunity and very high current ratio together with 5300 $V_{\rm RMS}$ insulation are achieved by coupling and LED with an integrated high gain photo detector in an eight pin dual-in-line package. Separate pins for the photo diode and output stage enable TTL compatible saturation voltages with high speed operation.

Access to the base terminal allows adjustment to the gain bandwidth.

The 6N139 is suited for low power logic applications involving CMOS and low power TTL applications. A 400 % current transfer ratio with only 0.5 mA of LED current is guaranteed.

Caution: Due to the small geometries of this device, it should be handled with Electrostatic Discharge (ESD) precautions. Proper grounding would prevent damage further and/or degradation which may be induced by ESD.

FEATURES

- High current transfer ratio, 500 %
- Low input current, 1.6 mA
- High common mode rejection, 500 V/µs
- Adjustable bandwidth-access to base
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912





RoHS COMPLIANT

APPLICATIONS

- Microprocessor system interface
- PLC, ATE input / output isolation
- EIA RS232 line receiver
- TTL, CMOS voltage level translation
- Multiplexed data transmission
- Digital control power supply
- Ground loop and electrical noise elimination

AGENCY APPROVALS

- UL 1577
- cUL
- DIN EN 60747-5-5 (VDE 0884-5), available with option 1



ORDERING INFORMATION						
6 N 1 3 PART NUMBER	# - X 0 # # T DIP Option 7 PACKAGE OPTION TAPE AND REEL 7.62 mm > 0.7 mm					
AGENCY CERTIFIED / PACKAGE	CTR (%)					
AGENCY CENTIFIED / PACKAGE	1.6 mA					
UL, cUL	> 500					
DIP-8	6N139					
SMD-8, option 7	6N139-X007T					
UL, cUL, VDE (option 1)	> 500					
DIP-8	6N139-X001					
SMD-8, option 7	6N139-X017T					

Note

· For additional information on the available options refer to option information

ABSOLUTE MAXIMUM RATINGS (T _{amb} = 25 °C, unless otherwise specified)								
PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT				
INPUT								
Reverse voltage		V_R	5	V				
Forward current		I _F	25	mA				
Average input current		I _{f(avg)}	20	mA				
Input power dissipation		P _{diss}	35	mW				
ОUТРUТ								
Supply and output voltage	Pin 8 to pin 5, pin 6 to pin 5	V_{CC}, V_{O}	0.5 to 18	V				
Emitter base reverse voltage	Pin 5 to pin 7		0.5	V				
Peak input current	50 % duty cycle - 1 ms pulse width		40	mA				
Peak transient input current	t _p ≤ 1 μs, 300 pps		1	Α				
Output current	Pin 6	I _O	60	mA				
Output power dissipation		P _{diss}	100	mW				
COUPLER								
Storage temperature		T _{stg}	-55 to +150	°C				
Operating temperature		T _{amb}	-55 to +100	°C				
Lead soldering temperature	t = 10 s	T _{sld}	260	°C				

Note

Stresses in excess of the absolute maximum ratings can cause permanent damage to the device. Functional operation of the device is not
implied at these or any other conditions in excess of those given in the operational sections of this document. Exposure to absolute
maximum ratings for extended periods of the time can adversely affect reliability.



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ELECTRICAL CHARACTERISTICS (T _{amb} = 25 °C, unless otherwise specified)							
PARAMETER	TEST CONDITION SYMBOL MIN.		TYP.	MAX.	UNIT		
INPUT							
Input forward voltage	I _F = 1.6 mA	V_{F}	ı	1.4	1.7	V	
Input reverse breakdown voltage	$I_R = 10 \mu A$	B _{VR}	5	-	-	V	
Input capacitance	$f = 1 MHz, V_F = 0$	C _{IN}	ı	25	-	pF	
Temperature coefficient of forward voltage	I _F = 1.6 mA		ı	-1.8	-	mV/°C	
OUTPUT							
	I_F = 1.6 mA, I_O = 8 mA, V_{CC} = 4.5 V	V_{OL}	ı	0.1	0.4	V	
Logic low, output voltage (1)	$I_F = 5 \text{ mA}, I_O = 15 \text{ mA}, V_{CC} = 4.5 \text{ V}$	V_{OL}	ı	0.15	0.4	V	
	$I_F = 12 \text{ mA}, I_O = 24 \text{ mA}, V_{CC} = 4.5 \text{ V}$	V_{OL}	ı	0.25	0.4	V	
Logic high, output current (1)	$I_F = 0 \text{ mA}, V_{CC} = 18 \text{ V}$	I _{OH}	ı	0.05	100	μA	
Logic low supply current (1)	$I_F = 1.6$ mA, $V_O = open$, $V_{CC} = 18$ V	I _{CCL}	ı	0.2	1.5	mA	
Logic high supply current (1)	$I_F = 0$ mA, $V_O = open$, $V_{CC} = 18 V$	I _{CCH}	-	0.001	10	μA	
COUPLER							
Input output insulation leakage current	45 % relative humidity, T_{amb} = 25 °C, t = 5 s, V_{IO} = 3000 V_{DC}		-	-	1	μA	
Coupling capacitance	f = 1 MHz	C _{IO}	-	0.6	-	pF	

Notes

⁽¹⁾ Pin 7 open

CURRENT TRANSFER RATIO						
PARAMETER	TEST CONDITION SYMBOL MIN. TYP. MAX. UNIT					UNIT
Current transfer ratio (1)	$I_F = 0.5 \text{ mA}, V_O = 0.4 \text{ V}, V_{CC} = 4.5 \text{ V}$	CTR	400	1600	-	%
Current transfer ratio (**)	$I_F = 1.6 \text{ mA}, V_O = 0.4 \text{ V}, V_{CC} = 4.5 \text{ V}$	CTR	500	2000	-	%

Notes

(1) Pin 7 open

SAFETY AND INSULATION RATINGS (T _{amb} = 25 °C, unless otherwise specified)							
PARAMETER	TEST CONDITION	TEST CONDITION SYMBOL		UNIT			
Climatic classification	According to IEC 68 part 1		55 / 100 / 21				
Comparative tracking index	Insulation group IIIa	CTI	175				
Maximum rated withstanding isolation voltage	According to UL 1577, t = 1 min	V _{ISO}	5300	V _{RMS}			
Maximum transient isolation voltage	According to DIN EN 60747-5-5	V _{IOTM}	8000	V _{peak}			
Maximum repetitive peak isolation voltage	According to DIN EN 60747-5-5	V _{IORM}	890	V _{peak}			
Isolation resistance	$T_{amb} = 25 ^{\circ}C, V_{IO} = 500 V$	R _{IO}	≥ 10 ¹²	Ω			
Isolation resistance	$T_{amb} = 100 ^{\circ}\text{C}, V_{IO} = 500 \text{V}$	R _{IO}	≥ 10 ¹¹	Ω			
Output safety power		P _{SO}	500	mW			
Input safety current		I _{SI}	300	mA			
Input safety temperature		T _S	175	°C			
Creepage distance	DIP-8		≥ 7	mm			
Clearance distance	DIF-0		≥ 7	mm			
Creepage distance	SMD-8, option 7,		≥ 8	mm			
Clearance distance	SMD-8		≥ 8	mm			
Insulation thickness		DTI	≥ 0.4	mm			

Note

As per IEC 60747-5-5, § 7.4.3.8.2, this optocoupler is suitable for "safe electrical insulation" only within the safety ratings. Compliance with
the safety ratings shall be ensured by means of protective circuits.

[•] Minimum and maximum values are testing requirements. Typical values are characteristics of the device and are the result of engineering evaluation. Typical values are for information only and are not part of the testing requirements.



SWITCHING CHARACTERISTICS						
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
Decreasing delections to logic loss at a stant	I_F = 0.5 mA, R_L = 4.7 k Ω	t _{PHL}	-	6	25	μs
Propagation delay time to logic low at output	I_F = 12 mA, R_L = 270 Ω	t _{PHL}	-	0.6	1	μs
Propagation delay time to logic high at output	I_F = 0.5 mA, R_L = 4.7 k Ω	t _{PLH}	-	4	60	μs
Propagation delay time to logic high at output	$I_F = 12 \text{ mA}, R_L = 270 \Omega$	t _{PLH}	-	1.5	7	μs

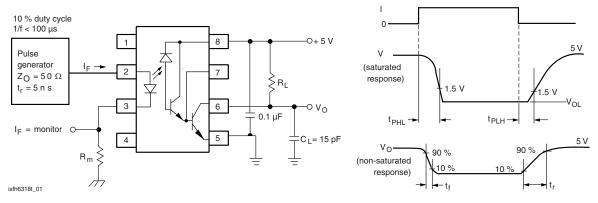


Fig. 1 - Switching Test Circuit

COMMON MODE TRANSIENT IMMUNITY						
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
Common mode transient immunity, logic high level output (1)	$I_F = 0$ mA, $R_L = 2.2$ k Ω , $R_{CC} = 0$, $ V_{CM} = 10$ V_{P-P}	CM _H	-	500	-	V/µs
Common mode transient immunity, logic low level output (1)	I_F = 16 mA, R_L = 2.2 kΩ, R_{CC} = 0, $ V_{CM} $ = 10 V_{P-P}	CM _L	-	500	-	V/µs

Note

(1) In applications where dV/dt may exceed 50 000 V/ μ s (such as state discharge) a series resistor, R_{CC} should be included to protect I_C from destructively high surge currents. The recommend value is R_{CC} \cong [(1 V)/(0.15 I_F (mA)] k Ω .

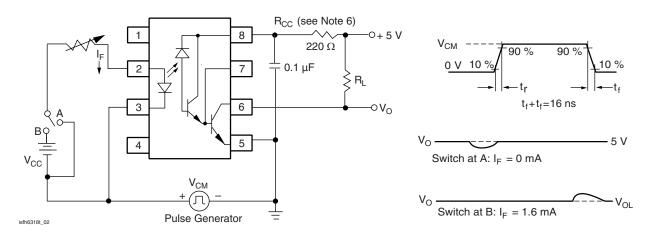


Fig. 2 - Test Circuit for Transient Immunity and Typical Waveforms



TYPICAL CHARACTERISTICS (T_{amb} = 25 °C, unless otherwise specified)

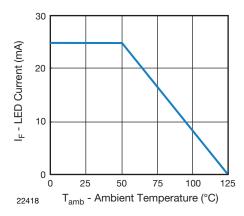


Fig. 2 - Permissible Forward LED Current vs. Temperature

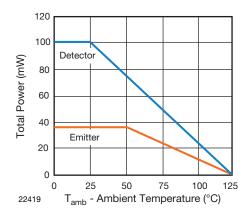
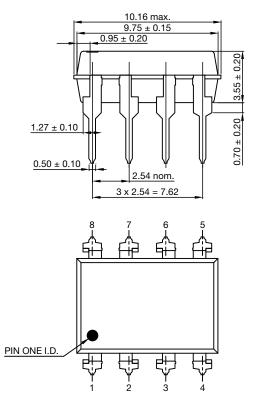
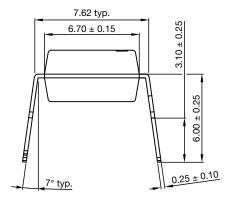


Fig. 3 - Permissible Power Dissipation vs. Temperature

PACKAGE DIMENSIONS (in millimeters)

DIP-8

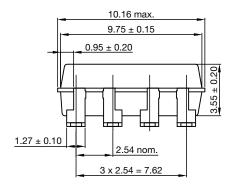


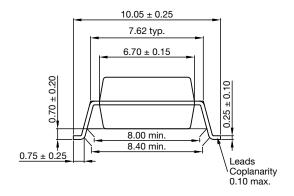


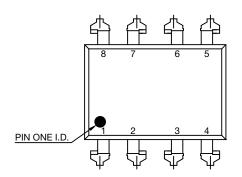
22672



SMD-8, Option 7







22674

PACKAGE MARKING

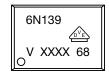


Fig. 3 - Example of 6N139-X017T

Note

- XXXX = LMC (lot marking code)
- VDE logo is only marked on option 1 parts
- Tape and reel suffix (T) is not part of the package marking

PACKING INFORMATION (in millimeters)

Tube

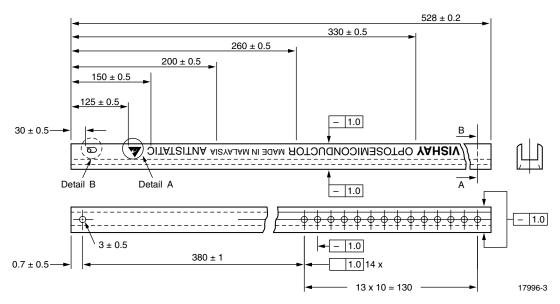


Fig. 4 - Shipping Tube Specifications for DIP-8 Packages

DEVICES PER TUBES			
TYPE	UNITS/TUBE	TUBES/BOX	UNITS/BOX
DIP-8	50	40	2000

DIP-8

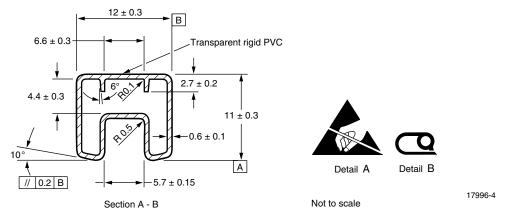


Fig. 5 - Tube Shipping Medium



Tape and Reel

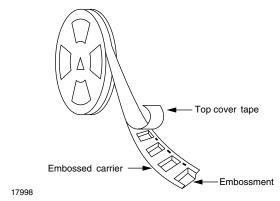


Fig. 6 - Tape and Reel Shipping Medium

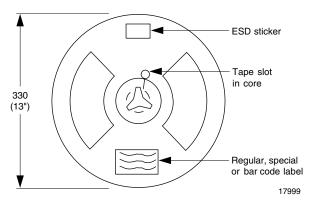


Fig. 7 - Tape and Reel Shipping Medium

SMD-8 (option 7)

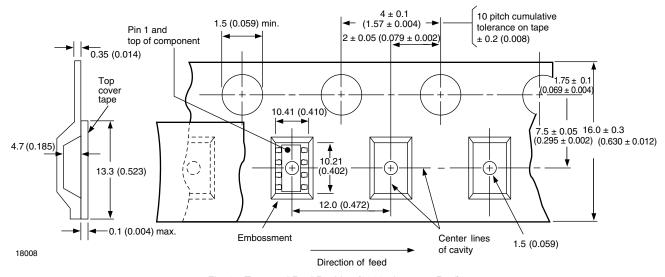


Fig. 8 - Tape and Reel Packing (1000 pieces on Reel)

SOLDER PROFILES

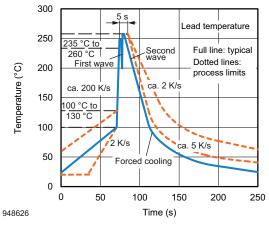


Fig. 9 - Wave Soldering Double Wave Profile According to J-STD-020 for DIP-8 Devices

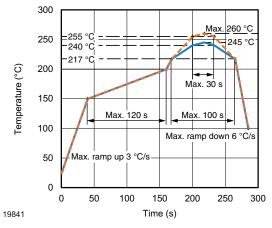


Fig. 10 - Lead (Pb)-free Reflow Solder Profile According to J-STD-020 for SMD-8 Devices



HANDLING AND STORAGE CONDITIONS

ESD level: HBM class 2 Floor life: unlimited

Conditions: T_{amb} < 30 °C, RH < 85 %

Moisture sensitivity level 1, according to J-STD-020



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